

Amendments to the Specification

Please replace the paragraph beginning at page 19, line 19, with the following amended paragraph:

The applicant has already obtained Japanese Patent No. ~~3313227~~ 3313277 for a method of production of an untreated copper foil. However, the method according to the above patent resulted in waviness on the rough surface even if the roughness of the surface was low and was not always suitable for copper foil for fine patterns.